


RCD8

RESIST COAT AND DEVELOP PLATFORM



RCD8 SOLUTIONS	
	<p>Features and Benefits</p> <ul style="list-style-type: none">+ Optional coating and spray/puddle developing in the same tool reduces footprint and capital investment+ Maximized application variety for lowest cost of ownership+ Ergonomic placement of all relevant elements for ease of use+ Easy transfer of processes from the RCD8 platform to a SUSS production tool due to compatible design+ All options are field upgradeable <p>Options</p> <ul style="list-style-type: none">+ Up to three additional modules can be controlled by one interface (coater, developer, hotplate, coolplate)+ Open bowl and/or GYRSET® coater+ Puddle and/or spray developer+ Lift pins (also for edge handling)+ Dispense arm (max. 4 dispense lines + 1 syringe system)+ Dispense options from <1 cps to 55000 cps+ Cleaning functions (nozzle, bowl, cotton candy for GYRSET®, edge of wafer, back side of wafer)

THE VERSATILE ALL-ROUNDER - RELIABILITY FROM SUSS MICROTEC+

The SUSS RCD8 system is the first tool that offers the option to convert from a spin coater with the patented GYRSET® closed cover coating technology to a spray developer within a few minutes.

The RCD8 coat and develop platform can be custom tailored anywhere from e.g. a basic manual spin coater to a semi automated GYRSET® enhanced coater and puddle & spray developer tool, serving for daily R&D work up to small scale production. Whenever changes are required over time, this versatile tool can be field upgraded with various options to perfectly match your future needs.

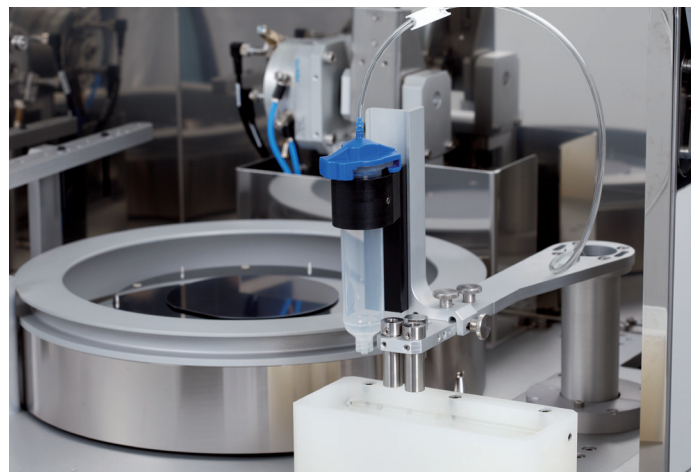
With its large variety of available chucks and configurations, literally all kind of substrate materials and shapes can be coated and developed on the RCD8. The platform can be equipped with various well proven dispense line and pump configurations for handling resists with viscosities from <1 cps up to 55000 cps.

UNIQUE GYRSET®

As an additional option the patented GYRSET® rotating closed cover coating technology can be integrated into the RCD8 spin coating module. For various photoresists and applications, the GYRSET® technology enables a wider process window and reduces material consumption significantly. Furthermore, square substrates and pieces can be coated all the way to the corners with a homogenous resist thickness.

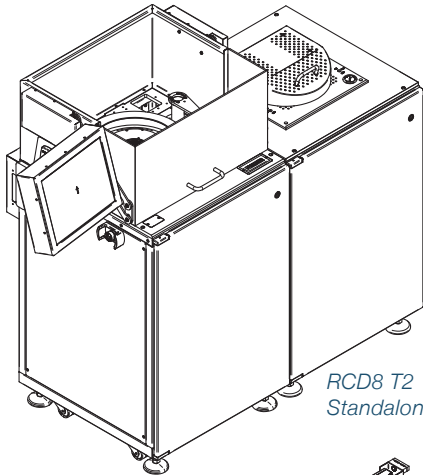
SOFTWARE

The standard software installed on the RCD8 platform is production proven and already installed on hundreds of SUSS systems worldwide. The control software is based on Windows XP and is shared with all other automated SUSS coating platforms allowing a flawless switch of systems. The touchscreen GUI (Graphical User Interface) monitors performance and status of the entire machine and tanks. With the intuitive software the operation of the tool is easy to acquire. The generation of process recipes is simplified by point-and-click ease.

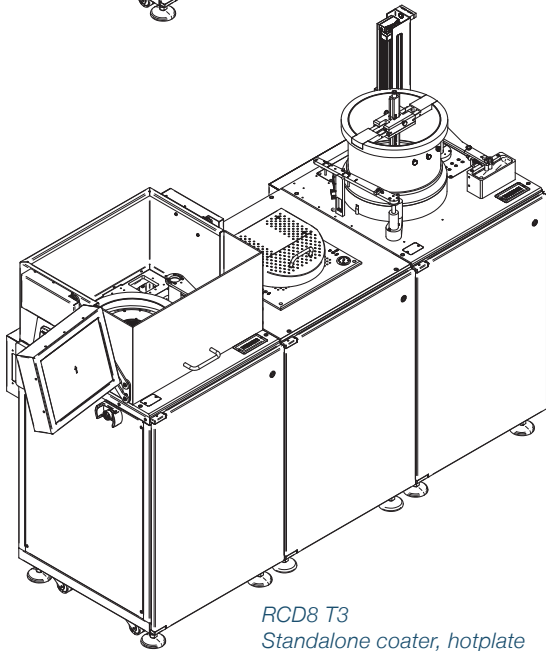


GYRSET® coater

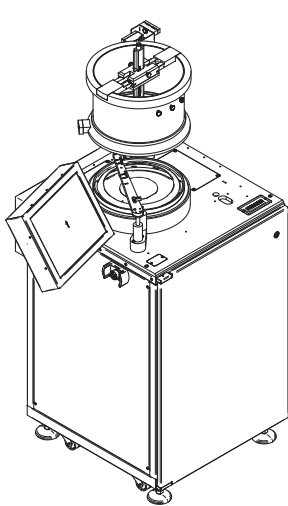
RESIST COAT AND DEVELOP PLATFORM



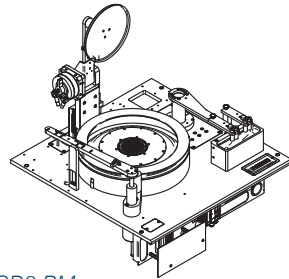
RCD8 T2
Standalone coater and hotplate



RCD8 T3
Standalone coater, hotplate
and spray developer



RCD8 T
Standalone developer



RCD8 BM
Bench mounted version
GYRSET® coater

TECHNICAL DATA

GENERAL

Substrate Size	2" to 8" round, 2" to 6" square
Substrate Handling	manual, optional: lift pins
User Interface	SUSS MMC Tool Control on Windows XP; industrial PC with touch screen control
Max. # of Recipes	unlimited
Max. # of Process Steps	50
Utilities	400 V, 16 A, 50 Hz, vacuum not needed, produced internally by N2 or CDA

MODULE: OPEN BOWL COATER

Spin Speed Max	12 000 rpm * ± 1 rpm (with hood)
Spin Acceleration	1 – 7 000 rpm/s *

MODULE: GYRSET® COATER

Spin Speed Max	3 000 rpm * ± 1 rpm with GYRSET®
Spin Acceleration	1 – 3 000 rpm/s *

MODULE: PUDDLE DEVELOPER

Waste	individual drain connection
Bowl Material	polyethylene
Nozzles	optional dispense arm with 3 lines (+ 3 lines on separate holder)

MODULE: SPRAY DEVELOPER

Waste	individual drain connection
Bowl Material	polyethylene
Nozzles	up to 3 in center + up to 2 on side (option: DI rinse, nitrogen purge)

MODULE: HOTPLATE (HP8)

Controller	via MMC Tool Control of RCD8 or optional separate controller
Temp. Range	60 - 250 °C (± 0.5 °C < 120 °C; ± 1 % ≥ 120 °C)
Options	proximity bake, nitrogen purge

MODULE: COOLPLATE (CP8)

Controller	via MMC Tool Control of RCD8 or optional separate controller
Max. Temp.	20 - 25 °C; ± 1 °C

* substrate and chuck dependent

Data, design and specification depend on individual process conditions and can vary according to equipment configurations. Not all specifications may be valid simultaneously. Illustrations, photos and specifications in this brochure are not legally binding. SUSS MicroTec reserves the right to change machine specifications without prior notice.

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